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**July 2015** 

# **FDMC012N03**

# N-Channel Power Trench<sup>®</sup> MOSFET 30 V, 1.23 m $\Omega$

## **Features**

- Max  $r_{DS(on)}$  = 1.23 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 35 A
- Max  $r_{DS(on)}$  = 1.46 m $\Omega$  at  $V_{GS}$  = 4.5 V,  $I_D$  = 32 A
- High performance technology for extremely low r<sub>DS(on)</sub>
- Termination is Lead-free
- RoHS Compliant

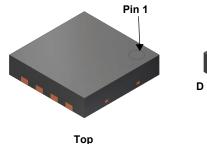


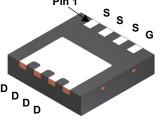
### **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

# **Application**

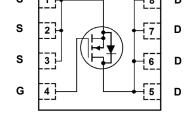
■ DC-DC Conversion





Bottom

Power 33



# MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol		Parame		Ratings	Units	
V <sub>DS</sub>	Drain to Source \	/oltage			30	V
V <sub>GS</sub>	Gate to Source V	oltage/			±12	V
	Drain Current	-Continuous	T <sub>C</sub> = 25 °C	(Note 5)	185	
		-Continuous	T <sub>C</sub> = 100 °C	(Note 5)	117	^
ID		-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	35	Α
		-Pulsed		(Note 4)	688	
E <sub>AS</sub>	Single Pulse Ava	lanche Energy		(Note 3)	337.5	mJ
D	Power Dissipatio	n	T <sub>C</sub> = 25 °C		64	W
$P_D$	Power Dissipatio	n	T <sub>A</sub> = 25 °C	(Note 1a)	2.3	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and St	Operating and Storage Junction Temperature Range				°C

## **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	1.95	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	53	C/VV

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC012N03	FDMC012N03	Power33	13 "	12 mm	3000 units

# **Electrical Characteristics** T<sub>J</sub> = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30			V
$\Delta BV_{DSS} \ \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, referenced to 25 °C		21		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V			1	μА
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>GS</sub> = ±12 V, V <sub>DS</sub> = 0 V			±100	nA

#### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	0.8	1.3	2.0	V
$\Delta V_{GS(th)} \ \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 μA, referenced to 25 °C		-4.5		mV/°C
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 35 A		0.96	1.23	
		$V_{GS} = 4.5 \text{ V}, I_D = 32 \text{ A}$		1.14	1.46	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 35 \text{ A}, T_J = 125 ^{\circ}\text{C}$		1.36	1.77	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DD</sub> = 5 V, I <sub>D</sub> = 35A		220		S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V -45 V V -0 V		5845	8183	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz		1440	2016	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 IMITZ		94	132	pF
$R_g$	Gate Resistance		0.1	0.5	1	Ω

# **Switching Characteristics**

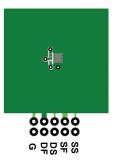
t <sub>d(on)</sub>	Turn-On Delay Time		16	29	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 35 A,	5.5	11	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_{GEN}$ = 6 $\Omega$	43	69	ns
t <sub>f</sub>	Fall Time		4.5	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V	78	110	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 15 \text{ V},$	35	50	nC
Q <sub>gs</sub>	Gate to Source Charge	I <sub>D</sub> = 35 A	11.5		nC
$Q_{gd}$	Gate to Drain "Miller" Charge		6		nC

### **Drain-Source Diode Characteristics**

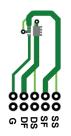
V <sub>SD</sub> Source	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 35 \text{ A}$ (Note 2)		8.0	1.3	V
	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2 \text{ A}$ (Note 2)		0.7	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	1 - 25 A di/dt - 100 A/		45	80	ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> = 35 A, di/dt = 100 A/μs		27.5	45	nC

Notes:

<sup>1.</sup> R<sub>0JA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0CA</sub> is determined by the user's board design.



53 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



130 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0%.
- 3.  $E_{AS}$  of 337.5 mJ is based on starting  $T_J$  = 25 °C, L = 3 mH,  $I_{AS}$  = 15 A,  $V_{DD}$  = 30 V,  $V_{GS}$  = 10 V. 100% test at L = 0.1 mH,  $I_{AS}$  = 47 A.
- 4. Pulsed Id please refer to Fig.11 SOA curve for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

# Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

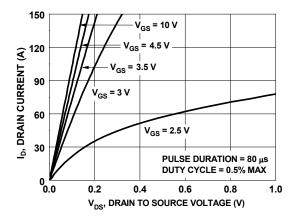


Figure 1. On Region Characteristics

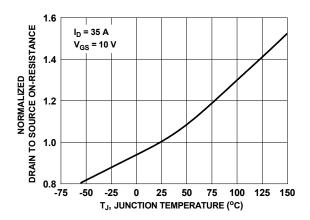


Figure 3. Normalized On Resistance vs Junction Temperature

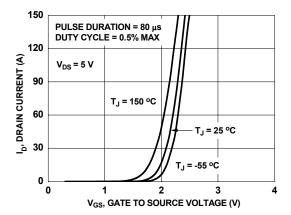


Figure 5. Transfer Characteristics

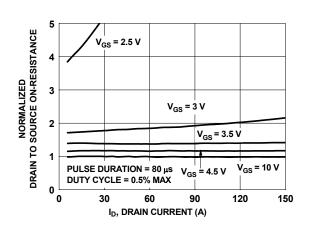


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

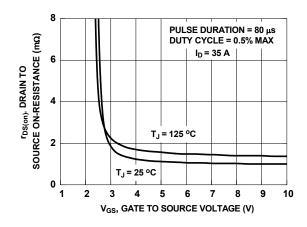


Figure 4. On-Resistance vs Gate to Source Voltage

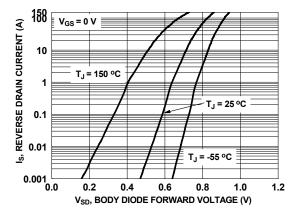


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# Typical Characteristics $T_J$ = 25 $^{\circ}$ C unless otherwise noted

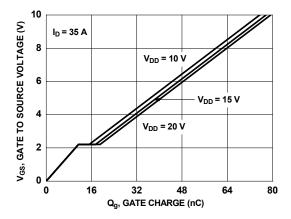


Figure 7. Gate Charge Characteristics

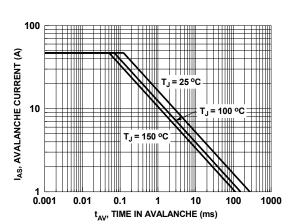


Figure 9. Unclamped Inductive Switching Capability

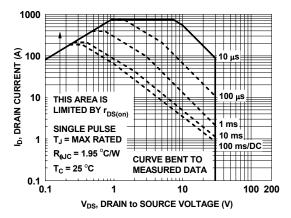


Figure 11. Forward Bias Safe Operating Area

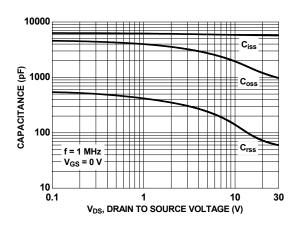


Figure 8. Capacitance vs Drain to Source Voltage

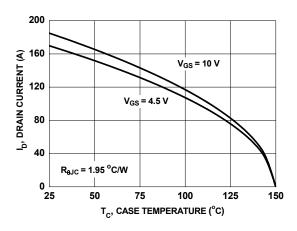


Figure 10. Maximum Continuous Drain Current vs Case Temperature

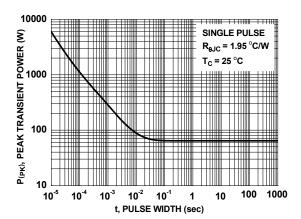


Figure 12. Single Pulse Maximum Power Dissipation

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

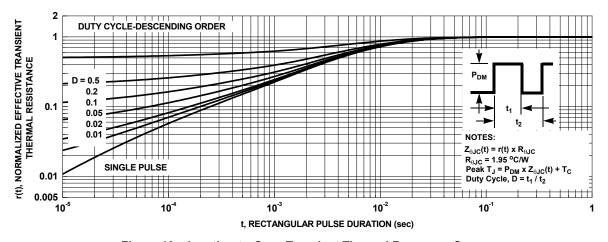
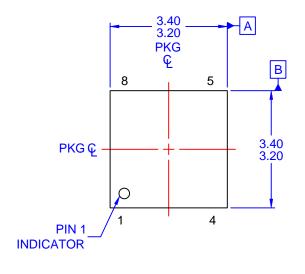
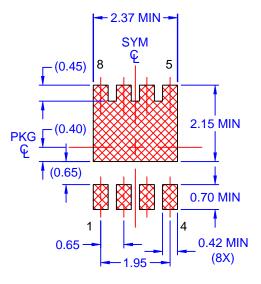
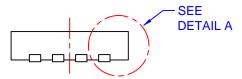


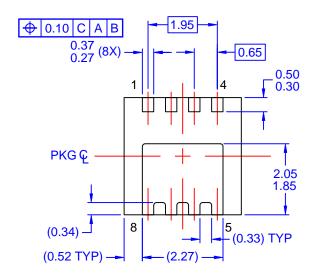
Figure 13. Junction-to-Case Transient Thermal Response Curve





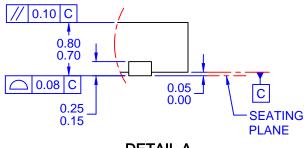


LAND PATTERN RECOMMENDATION



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